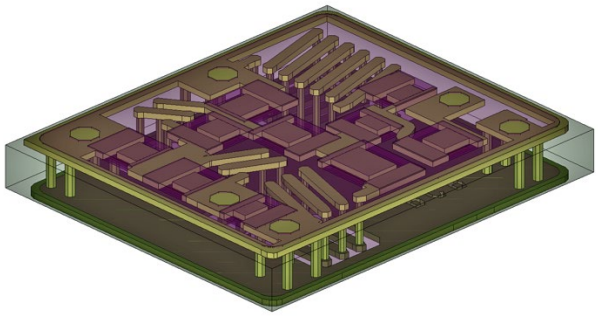
3D Glass Solutions Locks Process Flow for Integrative Passive Device Technology Node Process Design Kit

The Glass Ceramic-Based Technology Node Meets the Most Stringent Performance Requirements, Streamlining Custom Design and Fabrication of Radio Frequency Devices

ATLANTA – INTERNATIONAL MICROWAVE SYMPOSIUM – June 8, 2021 – 3D Glass Solutions (3DGS), a leading innovator of glass ceramic-based, three-dimensional passive radio frequency (RF) devices, today announced it has locked the process flow for its integrated passive device (IPD) technology node and solidified the IPD design rules in a process design kit (PDK) available for customer release. The locked process flow marks the industry's first glass ceramic-based IPD technology node and complimentary PDK, streamlining custom design and fabrication of high performance RF devices.



As the industry's first glass ceramic-based technology node, 3D Glass' integrative passive device process design kit streamlines custom design and fabrication of high performance RF devices

"Our powerful PDK software delivers over 95% simulation alignment to the final IPD product, which is unheard of in the RF community," says Mark Popovich, CEO of 3DGS. "This high alignment rate can be attributed to our unique glass ceramic platform and its ability to limit parasitic losses, which are often difficult to simulate. Our team is thrilled to have locked the process flow for this industry leading technology and we are ready to make it available to our customers."

The glass ceramic-based IPD technology is a low loss RF platform technology that significantly reduces power consumption in RF devices. Featuring high-Q inductors with Q-factors over 90 and high-Q capacitors with values over 250, the IPD technology node is ideally suited for frequencies between 0.1 and 10GHz. 3DGS' locked process flow significantly shortens manufacturing through put time for reduced time to market. The technology node's high yield, scalable process delivers a high correlation between simulation and final product for expedited product development. Designed in a compact, highly integrated electronic package, the IPD technology node can be used for the creation of:

- Filters
- Diplexers

- Couplers
- Bias tees
- Switch-bank filters
- Matching networks for Gallium Nitride (GaN) power amplifiers

The IPD technology node PDK is available for download now. For more information, contact sales@3dgsinc.com or (505) 916-5590. 3DGS is attending the 2021 Internal Microwave Symposium, June 8-9 in Atlanta, Georgia. Visit us at booth 1521 to learn more.

About 3D Glass Solutions

3D Glass Solutions (3DGS) is a world-class expert on the fabrication of electronic packages and devices using photo-definable glass-ceramics. The company manufactures a wide variety of glass-based, system-in-package (SiP) devices and components using its patented low-loss photosensitive APEX® glass ceramic technology for applications in RF electronics and photonics used in automotive radar, IC electronics, medical, aerospace, defense, wireless infrastructure, mobile handset and IoT industries. 3DGS offers high-precision products with exceptional high-frequency and low-loss properties. 3DGS glass ceramic-based RF products can be combined with any number of designs or devices to create incredibly unique and valuable SiP products. The company has created foundational patent positions related to all photosensitive glass-ceramic materials and devices and owns the fundamental intellectual property for all four positions (materials, design, systems and manufacturing) related to glass-ceramic devices for the electronics packaging industry. 3DGS leverages its unique product solutions to provide device manufacturing and systems integration services for several standard and custom products. To learn more about 3DGS, visit www.3DGSinc.com.

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